

Abstract

E11-P14

In wire bonding a semiconductor chip to the lead frame or other substrate, increase of productivity is achieved by letting the capillary which guides the wire between the wiring points (4, 5) move faster along its trajectory in the two travel stages (s1, s2). The capillary's drives in the horizontal (x, y) and vertical (z) directions are programmed by presetting the speed (vH) of the horizontal component of the movement and then calculating the vertical speed (vV) as a dependent variable based on the given trajectory. In determining said horizontal speed (vH) to be preset, the maximum horizontal and/or vertical acceleration values (aH*, aV*) associated with the drive mechanism are taken into account. Further time can be saved by letting the horizontal travel begin during the first travel stage (s1) and, by simultaneous vertical and horizontal travel, producing a steady transition (point k') from the first stage (s1) to the second (s2).

(Figures 6, 7)

This Sheet Has Been Replaced

